

104652-1 ✓ ACTIVE

AMPMODU | AMPMODU 50/50 Grid

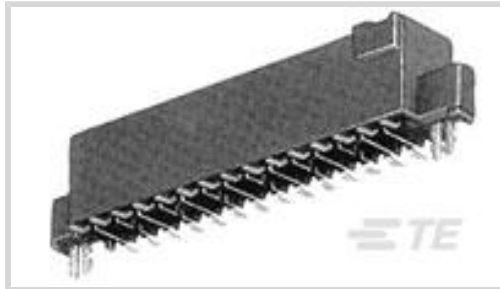
TE Internal #: 104652-1

AMPMODU 50/50 Grid, PCB Mount Receptacle, Vertical, Board-to-Board, 10 Position, 1.27mm [.05in] Centerline, Shrouded, Gold, Printed Circuit Board

[View on TE.com >](#)



Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **10**

Centerline (Pitch): **1.27 mm [.05 in]**

## Features

### Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Header Type	Shrouded
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Number of Rows	2
PCB Mount Orientation	Vertical
Number of Positions	10
Board-to-Board Configuration	Parallel

### Electrical Characteristics

Insulation Resistance	5000 M $\Omega$
Operating Voltage	30 VAC

### Body Features

PCB Retention Feature Material	Copper Alloy
PCB Retention Feature Plating Material	Tin-Lead over Nickel

### Contact Features

Mating Pin Diameter	150 $\mu$ m .46 mm[.018 in]
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PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 $\mu$ m[30 $\mu$ in]
Contact Type	Socket
Contact Current Rating (Max)	.5 A

### Termination Features

Rectangular Termination Post & Tail Thickness	.08 mm[.003 in]
Rectangular Termination Post & Tail Width	.36 mm[.014 in]
Termination Method to Printed Circuit Board	Surface Mount

### Mechanical Attachment

PCB Mount Retention Type	Hold-Down Post
Mating Alignment	With
Mating Alignment Type	Polarizing Tab
PCB Mount Retention	With
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

### Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Color	Black
Housing Material	LCP - GF (Liquid Crystal Polymer)

### Dimensions

Connector Height	4.75 mm[.187 in]
Row-to-Row Spacing	1.27 mm[.05 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]

### Usage Conditions

Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
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### Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

### Industry Standards

Approved Standards	CSA LR7189, UL E28476
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UL Flammability Rating

UL 94V-0

### Packaging Features

Packaging Quantity

49

Packaging Method

Box &amp; Tube, Tube

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU

Not Compliant

EU ELV Directive 2000/53/EC

Not Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUN 2020 (209)  
 Candidate List Declared Against: JUN 2020 (209)  
 Pb (13% in Component Part)

**Article Safe Usage Statements:**

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

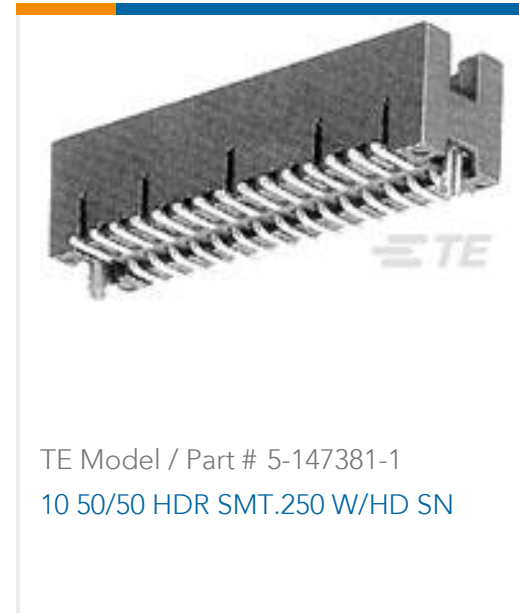
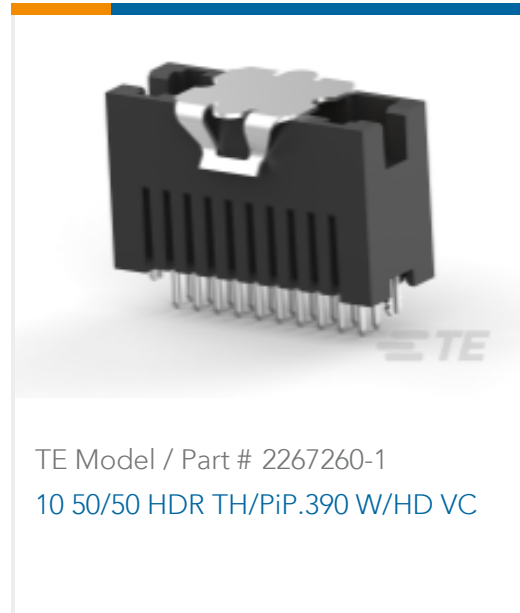
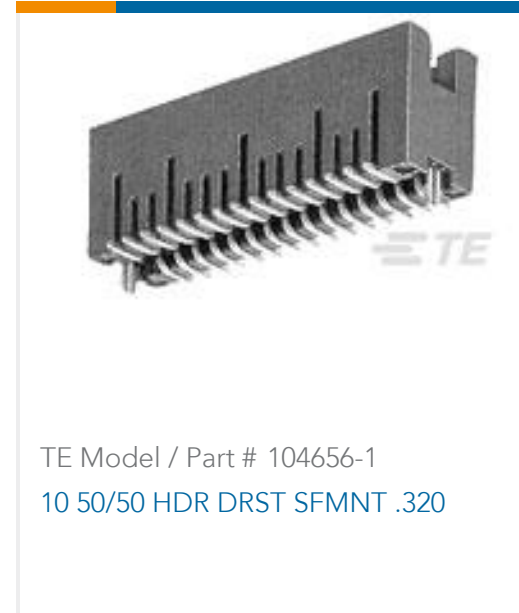
Solder Process Capability

Reflow solder capable to 260°C

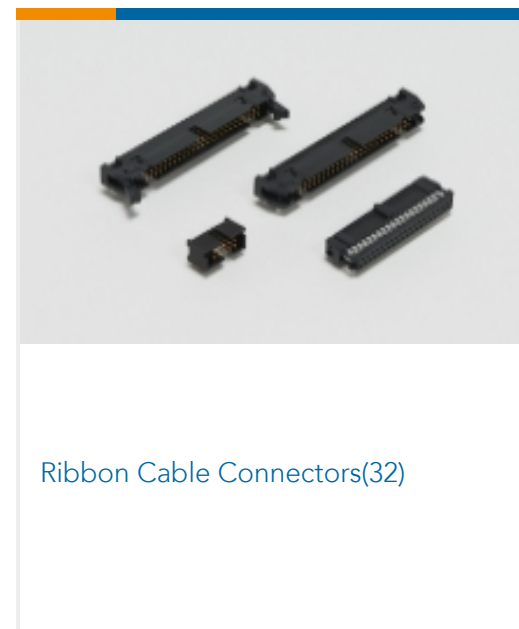
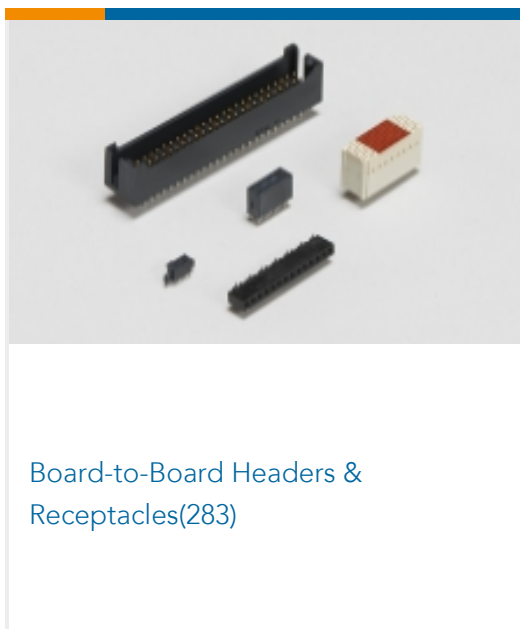
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

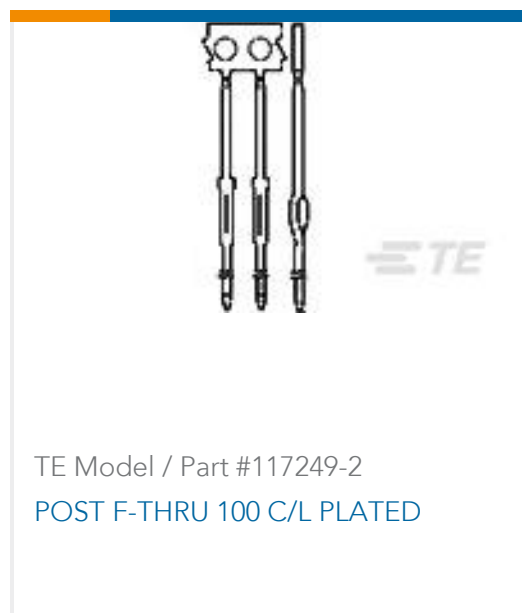
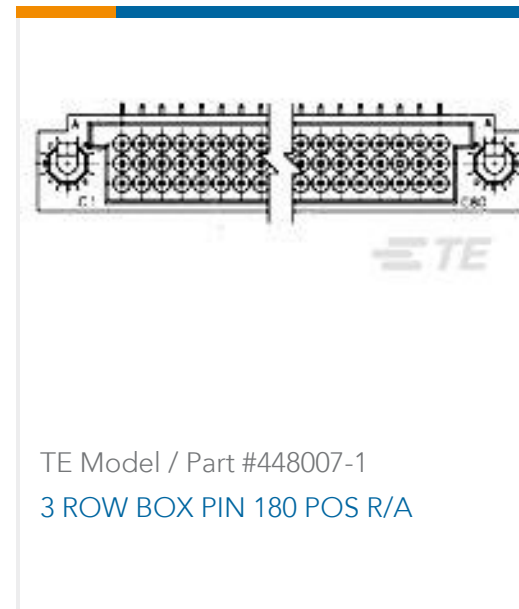
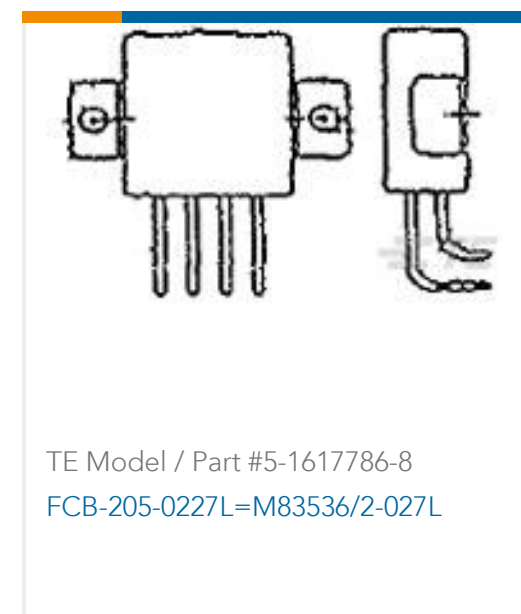
### Compatible Parts



Also in the Series | **AMPMODU 50/50 Grid**



Customers Also Bought



## Documents

### Product Drawings

10 50/50 GRID DRST SFMNT RCPT

English

### CAD Files

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_104652-1\\_L.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_104652-1\\_L.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_104652-1\\_L.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

## Product Specifications



### Application Specification

English

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### Product Environmental Compliance

#### TE Material Declaration

English

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### Agency Approvals

#### UL Report

English